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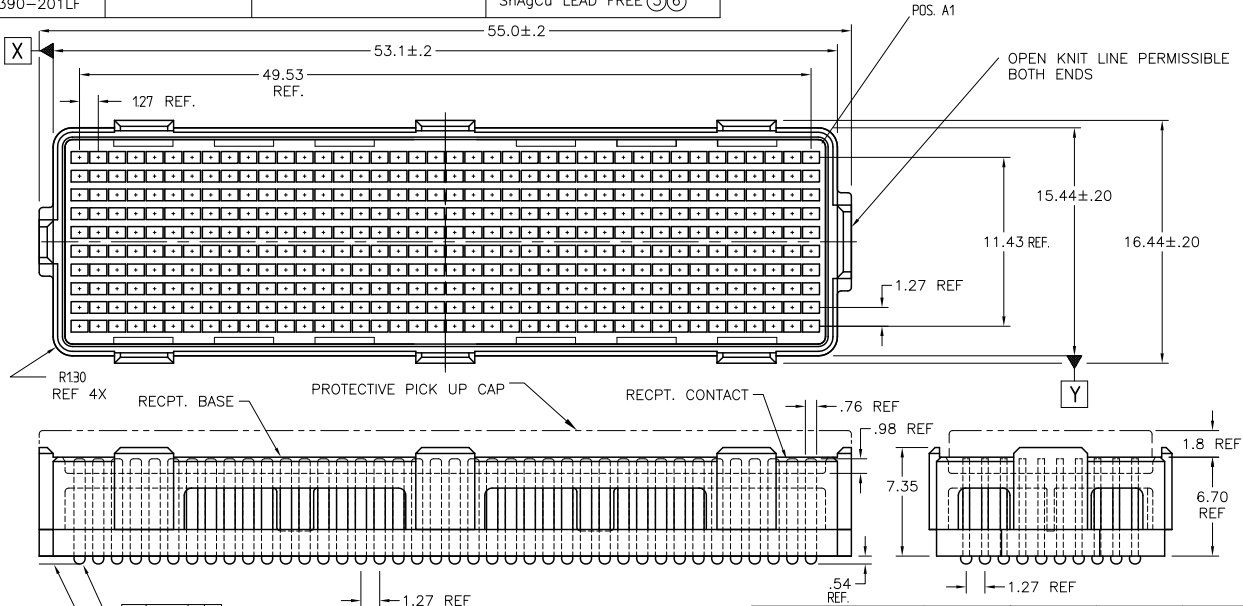
FCIconnect.com

1 | 2

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PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74390-001	YES	15u" (.38um) Au OVER Ni	SnPb
74390-001LF			SnAgCu LEAD FREE (5)(6)
74390-101	YES	30u" (.76um) Au OVER Ni	SnPb
74390-101LF			SnAgCu LEAD FREE (5)(6)
74390-201	YES	SEE NOTE 4.	SnPb
74390-201LF			SnAgCu LEAD FREE (5)(6)



⊕ ⌀.30 | X | Y

∕ .203

mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	ec'n no	dr	date	ASME Y14.5 ✓	ASME Y14.5
L	V06-0560	LP	2006-06-23	tolerances unless otherwise specified	angles
M	V09-0493	RE	2009-10-21	XX+3	XX+13
-	-	-	-	0° ± 2'	XXX+051
G	V00196	HJ	2000-07-02	dr	D. WAUGHEN
H	V20006	BRW	2002-01-03	engr	T. LEMKE
J	V03-0679	DAI	2003-06-19	chr	T. LEMKE
K	V04-0940	VS	2004-10-18	appd	T. LEMKE
sheet	revision	M	M	M	
index	sheet	1	2	3	

projection	product family
MM	MEG-ARRAY
scale 3:1	title
	8mm RECPT. ASSY
	10 X 40= 400 POS.
	dwg no
	74390
	sheet 1 of 3
	size A4
	type CUSTOMER Drawing

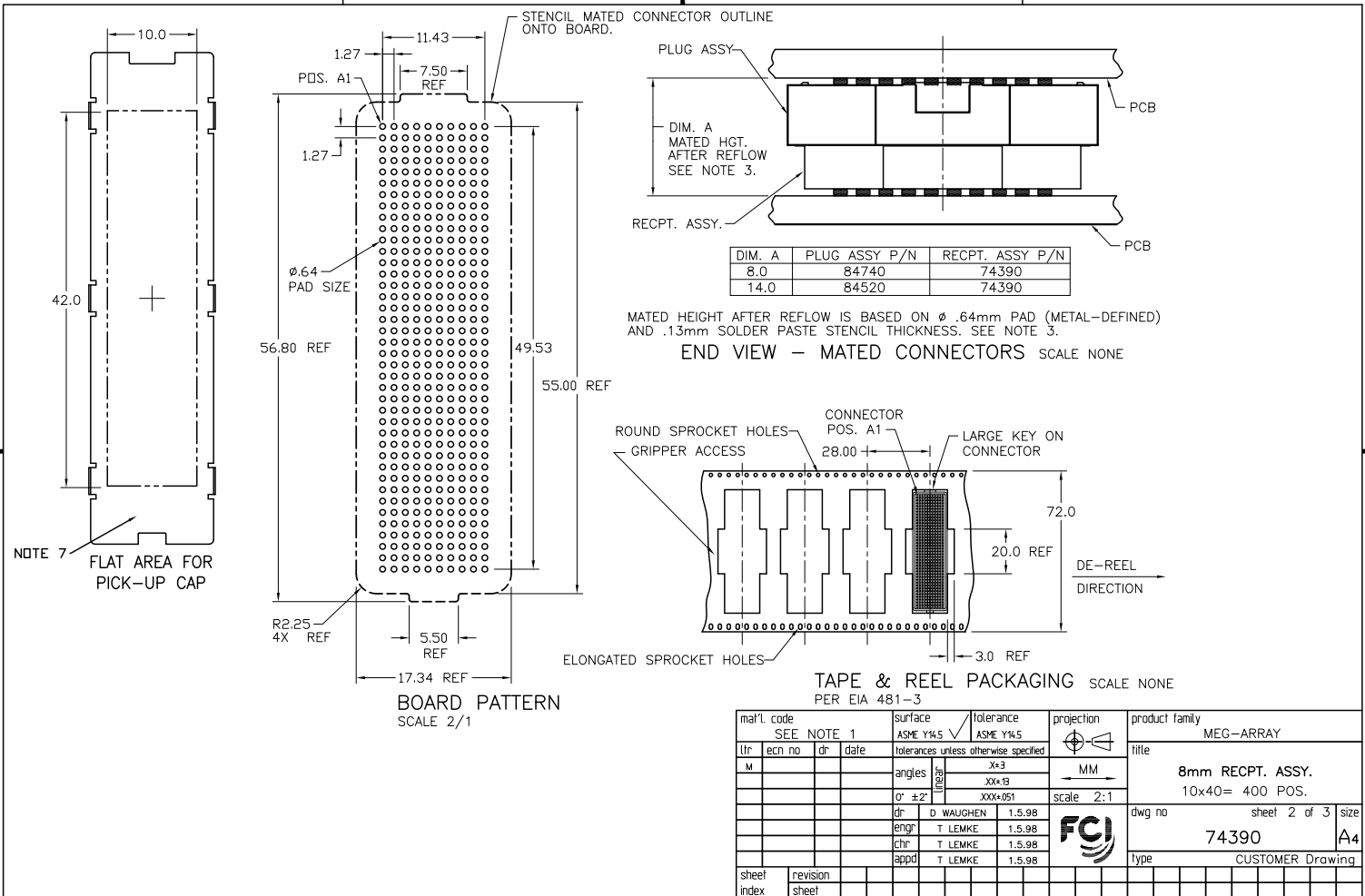
form A4mmXlc

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DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
8.0	84740	74390
14.0	84520	74390

MATED HEIGHT AFTER REFLOW IS BASED ON $\phi .64$ mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	ec'n no	ASME Y14.5	ASME Y14.5		MEG-ARRAY
	dr	tolerances unless otherwise specified		MM	title
M		angles	X=3	scale 2:1	8mm RECPT. ASSY. 10x40= 400 POS.
		0° ±2'	XX=19		dwg no
		dr	XXX=051		74390
		engr			sheet 2 of 3
		chr			A4
		appd			type
sheet index	revision sheet				CUSTOMER Drawing

NOTES:

- ①. **MAT'L:**
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING
CONTACT: (SEE TABLE ON SHEET1)
SOLDER BALL: (SEE TABLE ON SHEET1)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu
- ②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- ⑦. COMPANY LOGO TO APPEAR IN THIS AREA.

mat'l. code		SEE NOTE 1		surface		tolerance		projection		product family	
lfr	ecrn no	dr	date	ASME Y14.5 ✓		ASME Y14.5				MEG-ARRAY	
				tolerances unless otherwise specified		X=3		MM		title	
				angles		XX=19		scale 2:1		8mm RECPT. ASSY. 10x40= 400 POS.	
				0° ±2'		XXX+051				dwg no 74390 sheet 3 of 3 size A4	
				dr D WAUGHEN 1.5.98						type CUSTOMER Drawing	
				engr T LEMKE 1.5.98							
				chr T LEMKE 1.5.98							
				appd T LEMKE 1.5.98							
sheet index	revision sheet										